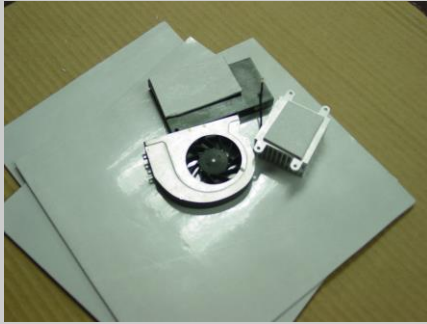


## THERMALLY CONDUCTIVE GAP FILLER 2.5W/m-K

### Features and Benefits

- 2.5W/m-K thermal conductivity
- Moderate compressibility
- Cost effective
- Electrically isolating



### Typical Applications

- Cooling component to the chassis, frame, or other type of heat spreader
- Mass storage device
- Heat pipe assemblies
- RDRAM memory modules
- Motor control
- Telecommunication hardware

### Optional Configurations

- Fibreglass reinforcements are recommended for  $\leq 0.03''$
- Adhesive coatings are optional
- Can be die-cut into specific dimensions

E-Fill 8100 Spec 01 is a performance-improved derivative of the original E-Fill 8100 gap pad. This special feature is benefited from a revised metal oxide filler matrix. It is electrically non-conductive and conforms to UL94 V0 standard.

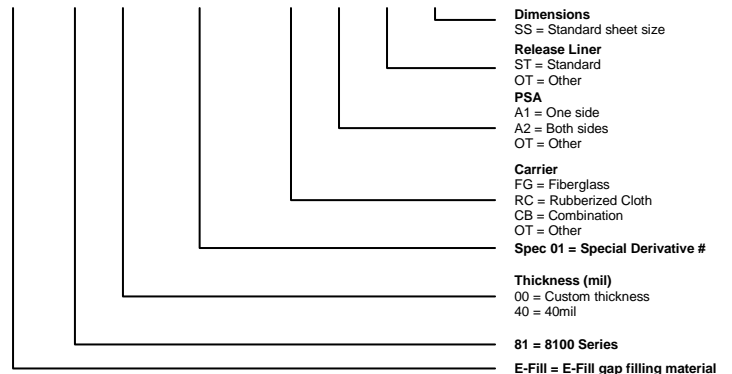
Properties	E-Fill 8100 Spec 01	Test Method
Construction & Composition	Soft silicone elastomer	—
Color	Grey	Visual
Thickness Range /inch (mm)	0.01"~0.30" (0.254~7.62) in 0.01" (0.254) increments	—
Standard Sheet Size	12" x 16"	—
Density /g.cm <sup>-3</sup>	2.43	—
Hardness /Shore 00	60	ASTM D2240
UL Flammability Rating	Conforms to UL94 V0 Standard	—
Temperature Range /°C	-40~200°C	—
Thermal Conductivity W.m <sup>-1</sup> .K <sup>-1</sup>	2.5	ASTM D5470 (modified)
Breakdown Voltage /V	>5000	ASTM D149
Shelf Life	24 months	—

Please contact us for other special requirements

Carrier Treatment	Criteria
Fiber Glass (FG)	Compulsory for $\leq 0.012''$ (0.3mm)
Rubberized Cloth (RC)	Not Recommended
Pressure Sensitive Adhesive (PSA)	Not Recommended
Detachable Adhesive (DA)	Not Recommended
Aluminum Foil (AL)	Not Recommended
Kapton (PI)	Not Recommended
Talc treatment (DAT)	Not Recommended

### Product Code and Descriptions

E-Fill 81 XX Spec 01 -XX -XX -XX -XX



#### Hong Kong

Tel: (852) 2686 8168  
Fax: (852) 2686 8268  
E-mail: emeihk@emeigroup.com

#### Dongguan

(86) 769-8334 1628  
(86) 769-8334 2028  
emeidg@emeigroup.com

#### Shanghai

(86) 21-5868 3381  
(86) 21-5868 3386  
emeish@emeigroup.com

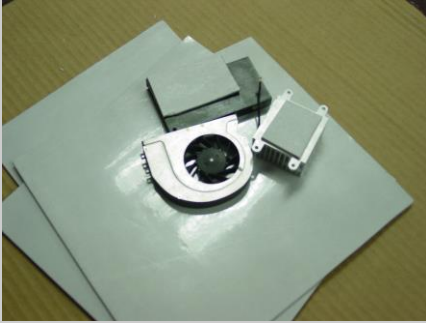
#### Taiwan

(886) 2-2793 9055  
(886) 2-2793 9501  
emeitw@emeigroup.com

[www.emeigroup.com](http://www.emeigroup.com)

## 产品特点

- 导热率 2.5W/m-K
- 中等压缩比
- 低成本
- 电绝缘



## 一般应用

- 高速大容量存储设备
- RDRAM 记忆模组
- 热管组件
- 底盘，框架或其他散热组件
- 电机控制器
- 无线通信硬件

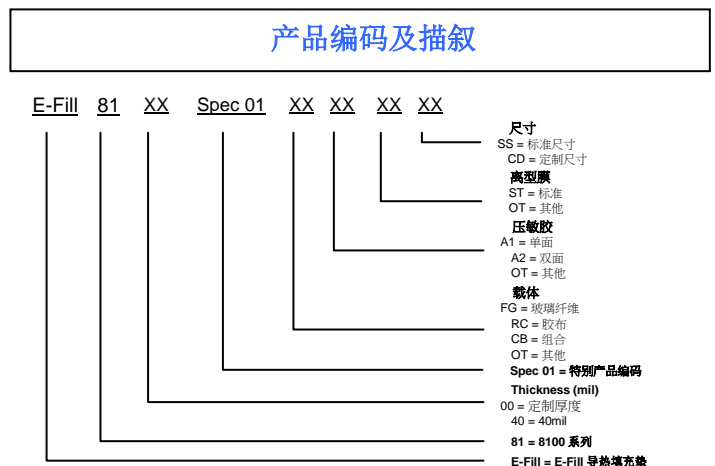
## 其他配置

- 产品厚度 ≤ 0.03"，建议使用玻璃纤维强化
- 可选择胶粘剂涂层
- 可模切成特定尺寸

E-Fill 8100 Spec 01 是基于 E-Fill 8100 改良而成的。新的氧化金属填充物料配方使 E-Fill 8100 Spec 01 的导热性能得到大幅的提升。E-Fill 8100 Spec 01 是电绝缘体而且达到 UL94V0 防火要求。

一般特性	E-Fill 8100 Spec 01	测试方法
结构及主要成分	硅树脂弹性体	—
颜色	灰色	目测
厚度 /inch (mm)	0.01"~0.30" (0.254~7.62) 以 0.01" (0.254)为基本增量单位	—
标准片材尺寸	12" x 16"	—
密度 /g.cm <sup>-3</sup>	2.43	—
硬度 /Shore 00	60	ASTM D2240
UL 燃烧等级	达到 UL94 V0 标准	—
使用温度 /°C	-40~200°C	—
导热率 W.m <sup>-1</sup> .K <sup>-1</sup>	2.5	ASTM D5470 (modified)
击穿电压/V	>5000	ASTM D149
有效期/Months	24	—
如对产品有特殊要求，请联络我们		

载体	标准
玻璃纤维 (FG)	厚度 ≤ 0.012" (0.3mm) 必须使用
胶布 (RC)	不建议使用
压敏胶 (PSA)	不建议使用
不粘胶 (DA)	不建议使用
铝箔 (AL)	不建议使用
聚酰亚胺膜 (PI)	不建议使用
滑石粉处理 (DAT)	不建议使用



香港  
Tel: (852) 2686 8168  
Fax: (852) 2686 8268  
E-mail: emeihk@emeigroup.com

东莞  
(86) 769-8334 1628  
(86) 769-8334 2028  
emeidg@emeigroup.com

上海  
(86) 21-5868 3381  
(86) 21-5868 3386  
emeish@emeigroup.com

台湾  
(886) 2-2793 9055  
(886) 2-2793 9501  
emeitw@emeigroup.com